

ZX5T955Z.

140V PNP Low saturation medium power transistor in SOT89

Summary

 $BV_{CEO} = -140V : R_{SAT} = 85m\Omega; I_C = -3A$

Description

Packaged in the SOT89 outline this new 5th generation low saturation 140V PNP transistor offers low on state losses making it ideal for use in DC-DC circuits, line switching and various driving and power management functions.

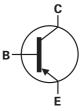


Features

- · 3 amps continuous current
- · Up to 10 amps peak current
- · Very low saturation voltages

Applications

- · Motor driving
- · Line switching
- · High side switches
- Subscriber line interface cards (SLIC)

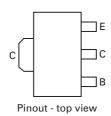


Ordering Information

| Device | Reel | Tape | Quantity | |
|-----------|------|-------|----------|--|
| | Size | Width | Per Reel | |
| ZX5T955TA | 7″ | 12mm | 1000 | |

Device Marking

955



Absolute maximum ratings

| Parameter | Symbol | Limit | Unit |
|--|-----------------------------------|-------------|------------|
| Collector-base voltage | BV _{CBO} | -180 | V |
| Collector-emitter voltage | BV _{CEO} | -140 | V |
| Emitter-base voltage | BV _{EBO} | -7 | V |
| Continuous collector current ^(a) | I _C | -3 | А |
| Peak pulse current | I _{CM} | -10 | Α |
| Power dissipation at T _{amb} =25°C ^(a) Linear derating factor | P _D | 1.5 12 | W mW/°C |
| Power dissipation at T _{amb} =25°C ^(b) Linear derating factor | P _D | 2.1 16.8 | W mW°C |
| Operating and storage temperature range | T _j , T _{stg} | -55 to 150 | °C |

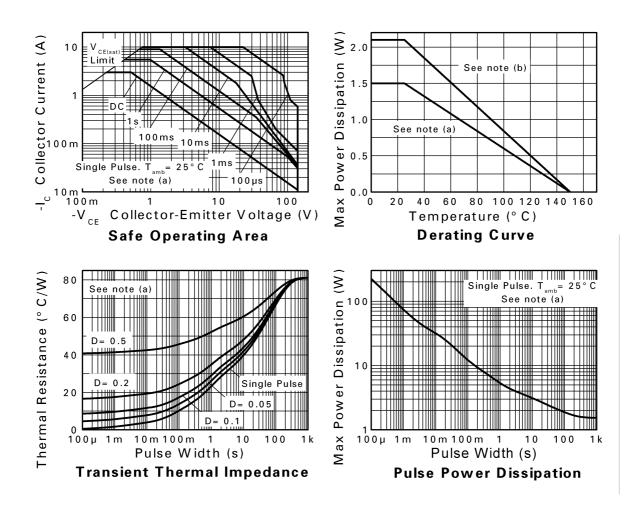
Thermal resistance

| Parameter | Symbol | Limit | Unit |
|------------------------------------|-----------------|-------|------|
| Junction to ambient ^(a) | $R_{\Theta JA}$ | 83 | °C/W |
| Junction to ambient ^(b) | $R_{\Theta JA}$ | 60 | °C/W |

⁽a) For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

⁽b) For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

Characteristics



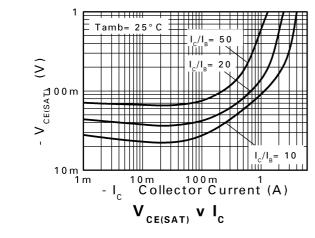
Electrical Characteristics (at T_{amb} =25°C unless otherwise stated)

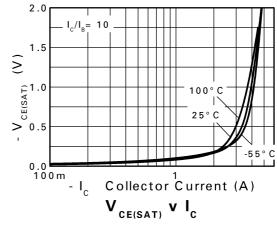
| Parameter | Symbol | Min. | Тур. | Max. | Unit | Conditions |
|-------------------------------------|---------------------------|------|------|-------------|----------|--|
| Collector-Base breakdown voltage | BV _{CBO} | -180 | -200 | | V | $I_C = -100 \mu A$ |
| Collector-Emitter breakdown voltage | BV _{CER} | -180 | -200 | | V | I_C = -100μA, RB<1k Ω |
| Collector-Emitter breakdown voltage | BV _{CEO} | -140 | -160 | | V | I _C = -10mA ^(*) |
| Emitter-Base breakdown voltage | BV _{EBO} | -7.0 | -8.0 | | V | $I_E = -100 \mu A$ |
| Collector cut-off current | I _{CBO} | | <1 | -20 -0.5 | nA μA | $V_{CB} = -150V$ $V_{CB} = -150V$, Tamb = 100°C |
| Collector cut-off current | I _{CER} R<1kΩ | | <1 | -20 -0.5 | nA μA | $V_{CB} = -150V$ $V_{CB} = -150V$, Tamb = 100°C |
| Emitter cut-off current | I _{EBO} | | <1 | -10 | nA | V _{EB} = -6V |
| Collector-Emitter saturation | V _{CE(sat)} | | -37 | -60 | mV | $I_C = -0.1A$, $I_B = -5mA^{(*)}$ |
| voltage | | | -50 | -75 | mV | $I_C = -0.5A, I_B = -50mA^{(*)}$ |
| | | | -80 | -115 | mV | $I_C = -1A$, $I_B = -100 \text{mA}^{(*)}$ |
| | | | -255 | -330 | mV | $I_C = -3A$, $I_B = -300 \text{mA}^{(*)}$ |
| Base-emitter saturation voltage | V _{BE(sat)} | | -910 | -1010 | mV | I _C = -3A, I _B = -300mA ^(*) |
| Base-emitter turn-on voltage | V _{BE(on)} | | -800 | -900 | mV | $I_C = -3A$, $V_{CE} = -5V^{(*)}$ |
| Static forward current | h _{FE} | 100 | 225 | | | $I_C = -10 \text{mA}, V_{CE} = -5 V^{(*)}$ |
| transfer ratio | | 100 | 200 | 300 | | $I_C = -1A$, $V_{CE} = -5V^{(*)}$ |
| | | 45 | 100 | | | $I_C = -3A$, $V_{CE} = -5V^{(*)}$ |
| | | | 5 | | | $I_C = -10A$, $V_{CE} = -5V^{(*)}$ |
| Transition frequency | f _T | | 120 | | MHz | I _C = -100mA, V _{CE} = -10V f = 50MHz |
| Output capacitance | C _{OBO} | | 33 | | pF | V _{CB} = -10V, f = 1MHz ^(*) |
| Switching times | t _{on} | | 42 | | ns | $I_C = -1A$, $V_{CC} = -50V$, |
| | t _{off} | | 636 | | ns | $I_{B1} = -I_{B2} = -100 \text{mA}$ |

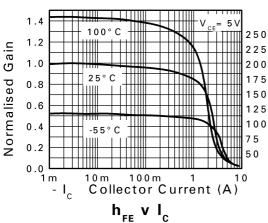
NOTES:

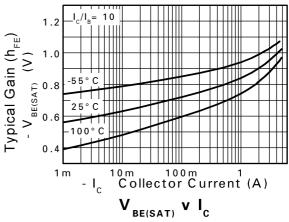
^(*) Measured under pulsed conditions. Pulse width ${\leq}300\mu\text{s};$ duty cycle ${\leq}2\%.$

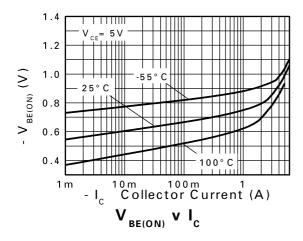
Typical characteristics



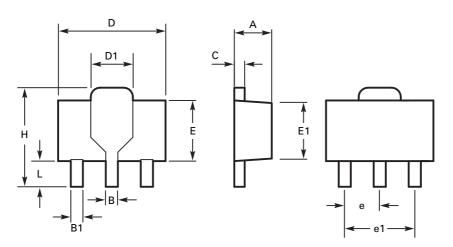








Package Outline



| DIM | Millimete | ers | Inch | nes | DIM | 1 Millimeters | | Inches | |
|-----|-----------|------|-------|-------|-----|---------------|------|--------|-------|
| | Min | Max | Min | Max | | Min | Max | Min | Max |
| Α | 1.40 | 1.60 | 0.550 | 0.630 | е | 1.40 | 1.50 | 0.055 | 0.059 |
| b | 0.38 | 0.48 | 0.015 | 0.019 | Е | 3.75 | 4.25 | 0.150 | 0.167 |
| b1 | - | 0.53 | - | 0.021 | E1 | - | 2.60 | - | 0.102 |
| b2 | 1.50 | 1.80 | 0.060 | 0.071 | G | 2.90 | 3.00 | 0.114 | 0.118 |
| С | 0.28 | 0.44 | 0.011 | 0.017 | Η | 2.60 | 2.85 | 0.102 | 0.112 |
| D | 4.40 | 4.60 | 0.173 | 0.181 | - | - | - | 1 | - |



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